

**BUGC20DAPH**

● **FEATURES**

- \* Halogen-free type
- \* Compliance to RoHS product
- \* Glass passivated chip
- \* Lead less chip form, no lead damage
- \* For surface mounted applications
- \* Low power loss, High efficiency
- \* Plastic package has Underwriters Laboratory Flammability Classification 94V-0

● **APPLICATION**

- \* General purpose rectification
- \* Surge absorption

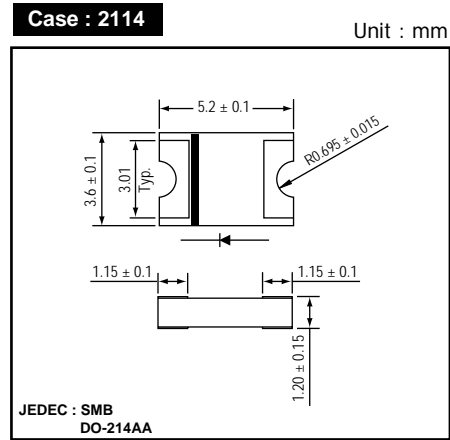
● **MECHANICAL DATA**

**Case :** Packed with FRP substrate and epoxy underfilled  
**Terminals :** Pure Tin plated (Lead-Free), solderable per MIL-STD-750, Method 2026.  
**Polarity :** Cathode Band, Laser marking

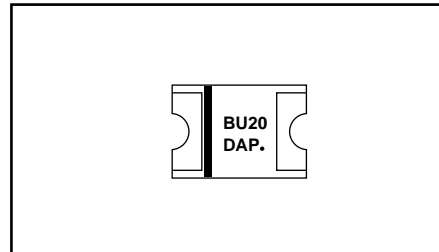
● **PACKING**

- \* 5,000 pieces per 13" (330mm ± 2mm) reel
- \* 2 reels per box
- \* 5 boxes per carton

● **OUTLINE DIMENSIONS**



● **MARKING**



**Absolute Maximum Ratings (Ta = 25 °C)**

ITEM	Symbol	Conditions	Rating	Unit
Repetitive peak reverse voltage	VRRM		200	V
Average forward current	IF(AV)		2.0	A
Peak forward surge current	IFSM	8.3ms single half sine-wave	50	A
Reverse recovery time	Trr	IF = 0.5A, IR = 1.0A, Irr = 0.25A	25	nS
Operating storage temperature Range	Tj, TSTG		-55 to +150	°C

**Electrical characteristics**

ITEM	Symbol	Conditions	Typ.	Max.	Unit
Forward voltage	VF	IF = 2.0A	0.92	1.0	V
Repetitive peak reverse current	IRRM	VR = Max. VRRM, Ta = 25 °C	0.20	3	uA
Junction capacitance	Cj	VR = 4V, f = 1.0 MHz	38	-	pF
Thermal resistance	Rth(JA)	Junction to ambient (NOTE 1)	66	-	°C/W
	Rth(JL)	Junction to lead (NOTE 1)	8	-	

NOTES : (1) Thermal resistance from junction to ambient and from junction to lead P.C.B. mounted on 0.2 x 0.2" (5.0 x 5.0mm) copper pad areas.  
 (2) Preliminary specification.

FIG.1 - FORWARD CURRENT DERATING CURVE

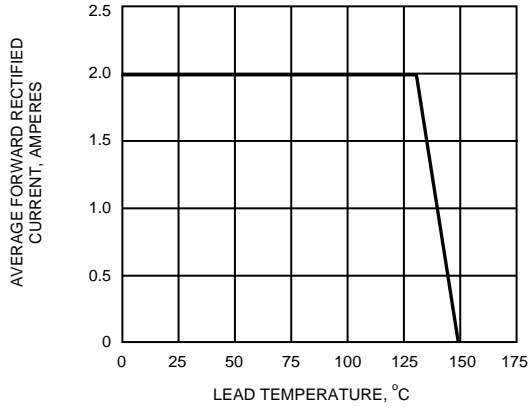


FIG.2 - MAXIMUM NON-REPETITIVE PEAK FORWARD SURGE CURRENT

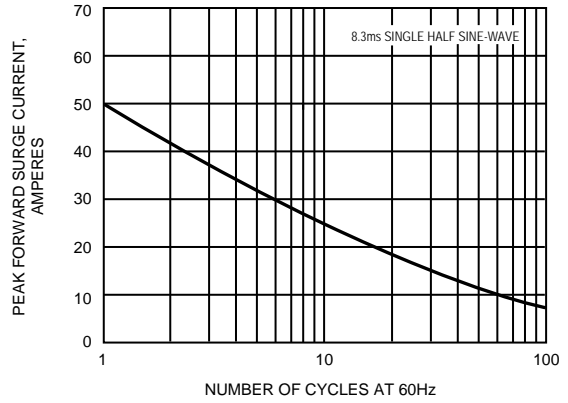


FIG.3 - TYPICAL INSTANTANEOUS FORWARD CHARACTERISTICS

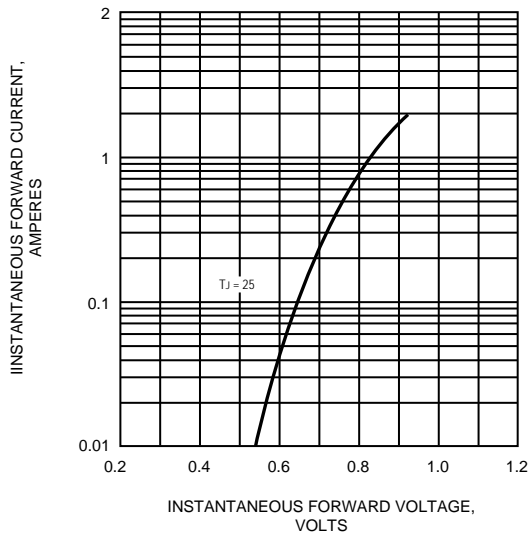


FIG.4 - TYPICAL REVERSE CHARACTERISTICS

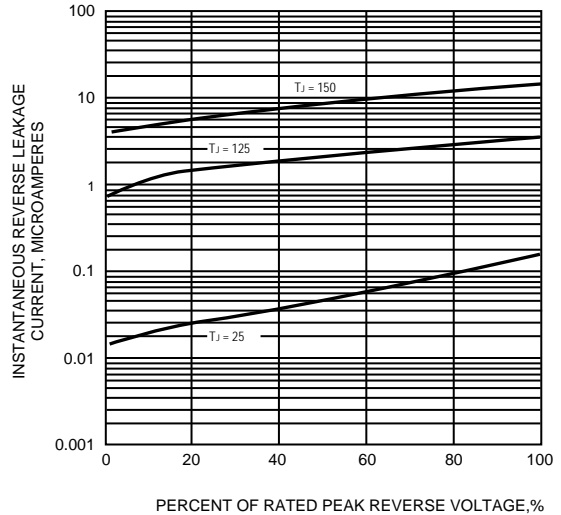


FIG.5 - TYPICAL JUNCTION CAPACITANCE

